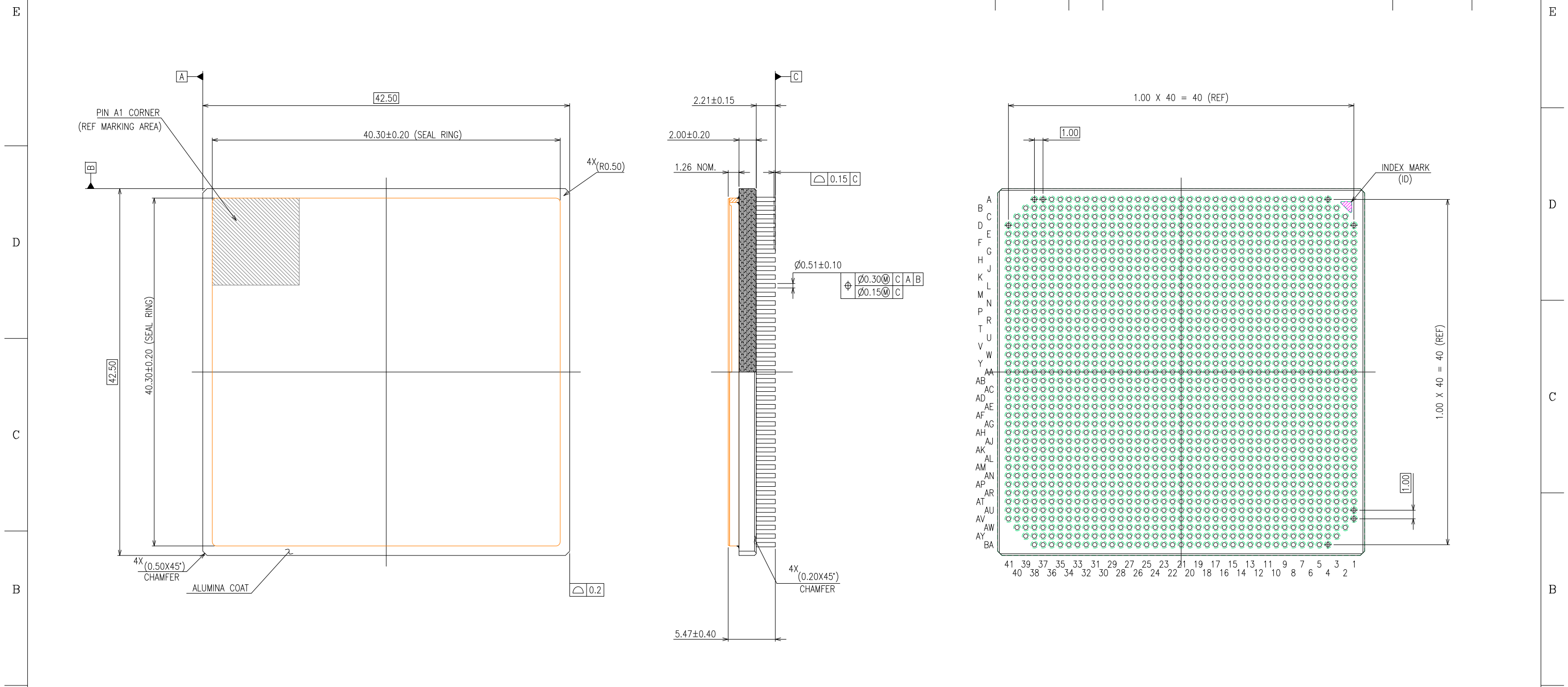


ECN NO.	REV.	DESCRIPTION OF CHANGE	EFFECTIVE DATE	ORIGINATOR
20160067	3	Lid flange thickness change to 0.156 per 1-24-11015	11/12/2015	Lijie Zhao
20160416	4	Delete material info. corrected dimensions.	07/06/2016	Erwin Q.
20160476	5	Add coplanarity specification.	08/11/2016	Erwin Q.



GENERAL TOLERANCE UNLESS OTHERWISE INDICATED DECIMAL                  ANGULAR ±0.20                          ±1°	PROJECTION 	MICROSEMI CORPORATION, SOC GROUP 3850 N 1st St San Jose, CA 95134	
	APPROVALS DRAWN: Erwin Quiobo CHECKED: Raymond Kuang	DATE 08/11/2016 08/11/2016	TITLE CG1657, 42.5 MM X 42.5 MM, 1.0 MM PITCH, 1657 SOLDER COLUMNS FLIP CHIP, CERAMIC COLUMN GRID ARRAY, PACKAGE OUTLINE DRAWING
DIMENSIONS: Millimeters (mm)	ENG'R: RELEASED:	VENDOR NAME: KYOCERA LID DWG. NUMBER: 1-24-11015	MSCC DWG. NUMBER: 1-14-11671 REV 5 VENDOR DWG. NUMBER: KD-YB5197 REV 0 SCALE: N.T.S. SHEET 1 OF 1